PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	POWER AND DISCRETES/25/16022
1.3 Title of PCI	Introduction of additional Reflow and Wire bonding parameters optimization on 6D48 in D2PAK/H2PAK.
1.4 Product Category	Pls refer to the listed product.
1.5 Issue date	2025-12-12

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Rosario RUGGERI
2.1.2 Marketing Manager	Anna RANIOLO
2.1.3 Quality Manager	Giuseppe D'URSO

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Methods	Process adjustment within specification limits when no reliability or quality risk has been highlighted by the risk assessment.	SH1A---ST SHENZHEN -CHINA

4. Description of change

	Old	**New**
4.1 Description	1 reflow + 10 Thermal cyles Wire Bonding power + force HL	2 reflow + 10 Thermal cyles Wire Bonding power + force NL
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on product final performance	

5. Reason / motivation for change

5.1 Motivation	To improve quality
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	ST Internal traceability

7. Timing / schedule

7.1 Date of qualification results	2025-12-05
7.2 Intended start of delivery	2026-01-11
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16022 6D48 WB & Reflow Optimization.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-12-12

9. Attachments (additional documentations)

16022 Public product.pdf
16022 6D48 WB & Reflow Optimization.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STH290N4F6-2AG	

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